

Title (en)

RECYCLING OF SILICON SAWING SLURRIES USING THERMAL PLASMA FOR THE PRODUCTION OF INGOTS OR WAFERS

Title (de)

RECYCLING VON SILICIUMSÄGESUSPENSIONEN MIT THERMISCHEM PLASMA ZUR HERSTELLUNG VON INGOTS ODER WAFERN

Title (fr)

RECYCLAGE DE BOUES DE SCIAGE DE SILICIUM POUR LA PREPARATION DE LINGOTS OU DE PLAQUES PAR PLASMA THERMIQUE

Publication

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Application

EP 11735480 A 20110610

Priority

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Abstract (en)

[origin: WO2012013876A1] A thermal, advantageously inductive, plasma is used to purify silicon from sawing slurries. For this purpose a thermal plasma is generated and a silicon-containing sawing slurry is subjected to the thermal plasma, so as to deposit silicon on a substrate.

IPC 8 full level

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CPC (source: EP US)

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